CD54HC165, CD74HC165, CD54HCT165, CD74HCT165

Data sheet acquired from Harris Semiconductor
SCHS156C

February 1998 - Revised October 2003

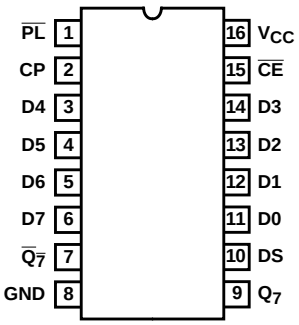
High-Speed CMOS Logic 8-Bit Parallel-In/Serial-Out Shift Register

Features

- **Buffered Inputs**
- **Asynchronous Parallel Load**
- **Complementary Outputs**
- **Fanout (Over Temperature Range)**
  - **Standard Outputs . . . . . 10 LSTTL Loads**
  - **Bus Driver Outputs . . . . . 15 LSTTL Loads**
- **Wide Operating Temperature Range . . . -55^{o}C to 125^{o}C**
- **Balanced Propagation Delay and Transition Times**
- **Significant Power Reduction Compared to LSTTL Logic ICs**
- **HC Types**
  - **2V to 6V Operation**
  - **High Noise Immunity: N_{IL} = 30%, N_{IH} = 30% of V_{CC} at V_{CC} = 5V**
- **HCT Types**
  - **4.5V to 5.5V Operation**
  - **Direct LSTTL Input Logic Compatibility, V_{IL}= 0.8V (Max), V_{IH} = 2V (Min)**
  - **CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL}, V_{OH}**

Pinout

CD54HC165, CD54HCT165
(CERDIP)
CD74HC165, CD74HCT165
(PDIP, SOIC)
TOP VIEW



Description

The 'HC165 and 'HCT165 are 8-bit parallel or serial-in shift registers with complementary serial outputs (Q_7 and $\overline{Q_7}$) available from the last stage. When the parallel load ($\overline{PL}$) input is LOW, parallel data from the D0 to D7 inputs are loaded into the register asynchronously. When the $\overline{PL}$ is HIGH, data enters the register serially at the DS input and shifts one place to the right ($Q_0 \rightarrow Q_1 \rightarrow Q_2$, etc.) with each positive-going clock transition. This feature allows parallel-to-serial converter expansion by typing the Q_7 output to the DS input of the succeeding device.

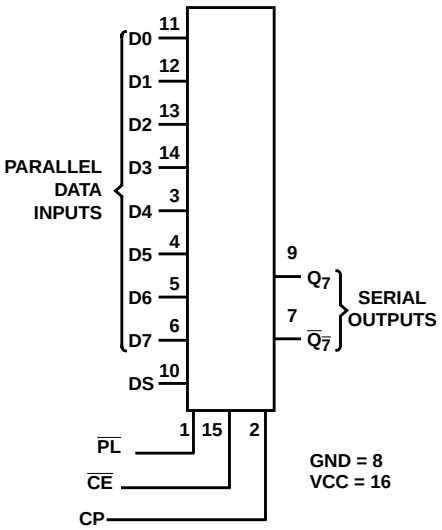
For predictable operation the LOW-to-HIGH transition of $\overline{CE}$ should only take place while CP is HIGH. Also, CP an d $\overline{CE}$ should be LOW before the LOW-to-HIGH transition of PL to prevent shifting the data when $\overline{PL}$ goes HIGH.

Ordering Information

PART NUMBER	TEMP. RANGE (^{o}C)	PACKAGE
CD54HC165F3A	-55 to 125	16 Ld CERDIP
CD54HCT165F3A	-55 to 125	16 Ld CERDIP
CD74HC165E	-55 to 125	16 Ld PDIP
CD74HC165M	-55 to 125	16 Ld SOIC
CD74HC165MT	-55 to 125	16 Ld SOIC
CD54HC165M96	-55 to 125	16 Ld SOIC
CD74HCT165E	-55 to 125	16 Ld PDIP
CD74HCT165M	-55 to 125	16 Ld SOIC
CD74HCT165MT	-55 to 125	16 Ld SOIC
CD54HCT165M96	-55 to 125	16 Ld SOIC

NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel. The suffix T denotes a small-quantity reel of 250.

Functional Diagram



TRUTH TABLE

OPERATING MODE	INPUTS					Q_n REGISTER		OUTPUTS	
	$\overline{PL}$	$\overline{CE}$	CP	DS	D0 - D7	Q_0	Q_1 - Q_6	Q_7	$\overline{Q}_7$
Parallel Load	L	X	X	X	L	L	L-L	L	H
	L	X	X	X	H	H	H-H	H	L
Serial Shift	H	L	↑	l	X	L	q_0 - q_5	q_6	$\overline{q}_6$
	H	L	↑	h	X	H	q_0 - q_5	q_6	$\overline{q}_6$
Hold Do Nothing	H	H	X	X	X	q_0	q_1 - q_6	q_7	$\overline{q}_7$

H =High Voltage Level
h = High Voltage Level One Set-up Time Prior To The Low-to-high Clock Transition
l = Low Voltage Level One Set-up Time Prior To The Low-to-high Clock Transition
L = Low Voltage Level
X = Don't Care
↑ = Transition from Low to High Level
q_n = Lower Case Letters Indicate The State Of the Reference Output Clock Transition

Absolute Maximum Ratings

DC Supply Voltage, V_{CC} . . . . . -0.5V to 7V
DC Input Diode Current, I_{IK}
For V_I < -0.5V or V_I > V_{CC} + 0.5V . . . . . ±20mA
DC Output Diode Current, I_{OK}
For V_O < -0.5V or V_O > V_{CC} + 0.5V . . . . . ±20mA
DC Drain Current per Output, IO
For V_O < -0.5V V_O > V_{CC} + 0.5V . . . . . ±25mA
DC Output Source or Sink Current per Output Pin, I_O
For V_O > -0.5V or V_O < V_{CC} + 0.5V . . . . . ±25mA
DC V_{CC} or Ground Current, I_{CC} or I_{GND} . . . . . ±50mA

Operating Conditions

Temperature Range (T_A) . . . . . -55°C to 125°C
Supply Voltage Range, V_{CC}
HC Types . . . . . .2V to 6V
HCT Types . . . . . .4.5V to 5.5V
DC Input or Output Voltage, V_I, V_O . . . . . 0V to V_{CC}
Input Rise and Fall Time
2V . . . . . 1000ns (Max)
4.5V. . . . . 500ns (Max)
6V . . . . . 400ns (Max)

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} (°C/W)
E (PDIP) Package	67
M (SOIC) Package	73

Maximum Junction Temperature . . . . . 150°C
Maximum Storage Temperature Range . . . . . -65°C to 150°C
Maximum Lead Temperature (Soldering 10s) . . . . . 300°C
(SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS V_I (V)	TEST CONDITIONS I_O (mA)	TEST CONDITIONS V_{CC} (V)	25°C MIN	25°C TYP	25°C MAX	-40°C TO 85°C MIN	-40°C TO 85°C MAX	-55°C TO 125°C MIN	-55°C TO 125°C MAX	UNITS
HC TYPES												
High Level Input Voltage	V_{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V_{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	µA

DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V_I (V)	I_O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	6	-	-	8	-	80	-	160	µA
HCT TYPES												
High Level Input Voltage	V_{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V_{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} to GND	0	5.5	-	-	±0.1	-	±1	-	±1	µA
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	5.5	-	-	8	-	80	-	160	µA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI_{CC} (Note 2)	V_{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	µA

NOTE:

2. For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
DS, D0 to D7	0.35
CP, $\overline{PL}$	0.65

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Specifications table, e.g. 360µA max at 25°C.

Prerequisite For Switching Specifications

PARAMETER	SYMBOL	V_{CC} (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	MAX	MIN	MAX	MIN	MAX	
HC TYPES									
CP Pulse Width	t_{WL}, t_{WH}	2	80	-	100	-	120	-	ns
		4.5	16	-	20	-	24	-	ns
		6	14	-	17	-	20	-	ns

Prerequisite For Switching Specifications (Continued)

PARAMETER	SYMBOL	V_{CC} (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	MAX	MIN	MAX	MIN	MAX	
$\overline{PL}$ Pulse Width	t_{WL}	2	80	-	100	-	120	-	ns
		4.5	16	-	20	-	24	-	ns
		6	14	-	17	-	20	-	ns
Set-up Time DS to CP	t_{SU}	2	80	-	100	-	120	-	ns
		4.5	16	-	20	-	24	-	ns
		6	14	-	17	-	20	-	ns
$\overline{CE}$ to CP	$t_{SU(L)}$	2	80	-	100	-	120	-	ns
		4.5	16	-	20	-	24	-	ns
		6	14	-	17	-	20	-	ns
D0-D7 to $\overline{PL}$	t_{SU}	2	80	-	100	-	120	-	ns
		4.5	16	-	20	-	24	-	ns
		6	14	-	17	-	20	-	ns
Hold Time DS to CP or $\overline{CE}$	t_H	2	35	-	45	-	55	-	ns
		4.5	7	-	9	-	11	-	ns
		6	6	-	8	-	9	-	ns
$\overline{CE}$ to CP	t_H	2	0	-	0	-	0	-	ns
		4.5	0	-	0	-	0	-	ns
		6	0	-	0	-	0	-	ns
Recovery Time $\overline{PL}$ to CP	t_{REC}	2	100	-	125	-	150	-	ns
		4.5	20	-	25	-	30	-	ns
		6	17	-	21	-	26	-	ns
Maximum Clock Pulse Frequency	f_{MAX}	2	6	-	5	-	4	-	MHz
		4.5	30	-	24	-	20	-	MHz
		6	35	-	28	-	24	-	MHz
HCT TYPES									
CP Pulse Width	t_{WL}, t_{WH}	4.5	18	-	23	-	27	-	ns
$\overline{PL}$ Pulse Width	t_{WL}	4.5	20	-	25	-	30	-	ns
Set-up Time DS to CP	t_{SU}	4.5	20	-	25	-	30	-	ns
$\overline{CE}$ to CP	$t_{SU(L)}$	4.5	20	-	25	-	30	-	ns
D0-D7 to $\overline{PL}$	t_{SU}	6	20	-	25	-	30	-	ns
Hold Time DS to CP or $\overline{CE}$	t_H	4.5	7	-	9	-	11	-	ns
$\overline{CE}$ to CP	t_S, t_H	4.5	0	-	0	-	0	-	ns
Recovery Time $\overline{PL}$ to CP	t_{REC}	4.5	20	-	25	-	30	-	ns
Maximum Clock Pulse Frequency	f_{MAX}	4.5	27	-	22	-	18	-	MHz

Switching Specifications Input t_r, t_f = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C		-40°C TO 85°C	-55°C TO 125°C	UNITS
				TYP	MAX	MAX	MAX	
HC TYPES								
Propagation Delay	t_{PLH}, t_{PHL}	C_L = 50pF	2	-	165	205	250	ns
CP or $\overline{CE}$ to Q_7 or $\overline{Q_7}$			4.5	-	33	41	50	ns
		C_L = 15pF	5	13	-	-	-	ns
		C_L = 50pF	6	-	28	35	43	ns
$\overline{PL}$ to Q_7 or $\overline{Q_7}$	t_{PLH}, t_{PHL}	C_L = 50pF	2	-	175	220	265	ns
			4.5	-	35	44	53	ns
		C_L = 15pF	5	14	-	-	-	ns
		C_L = 50pF	6	-	30	37	45	ns
D7 to Q_7 or $\overline{Q_7}$	t_{PLH}, t_{PHL}	C_L = 50pF	2	-	150	190	225	ns
			4.5	-	30	38	45	ns
		C_L = 15pF	5	12	-	-	-	ns
		C_L = 50pF	6	-	26	33	38	ns
Output Transition Times	t_{TLH}, t_{THL}	C_L = 50pF	2	-	75	95	110	ns
			4.5	-	15	19	22	ns
			6	-	13	16	19	ns
Input Capacitance	C_{IN}	-	-	-	10	10	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C_{PD}	-	5	17	-	-	-	pF
HCT TYPES								
Propagation Delay	t_{PLH}, t_{PHL}	C_L = 50pF	4.5	-	40	50	60	ns
CP or $\overline{CE}$ to Q_7 or $\overline{Q_7}$		C_L = 15pF	5	17	-	-	-	ns
$\overline{PL}$ to Q_7 or $\overline{Q_7}$	t_{PLH}, t_{PHL}	C_L = 50pF	4.5	-	40	50	60	ns
		C_L = 15pF	5	17	-	-	-	ns
D7 to Q_7 or $\overline{Q_7}$	t_{PLH}, t_{PHL}	C_L = 50pF	4.5	-	35	44	53	ns
		C_L = 15pF	5	14	-	-	-	ns
Output Transition Times	t_{TLH}, t_{THL}	C_L = 50pF	4.5	-	15	19	22	ns
Input Capacitance	C_{IN}	C_L = 50pF	-	-	10	10	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C_{PD}	-	5	24		-	-	pF

NOTES:

3. C_{PD} is used to determine the dynamic power consumption, per package.
4. $P_D = V_{CC}^2 f_i + \Sigma (C_L V_{CC}^2 + f_O)$ where f_i = Input Frequency, f_O = Output Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

Test Circuits and Waveforms

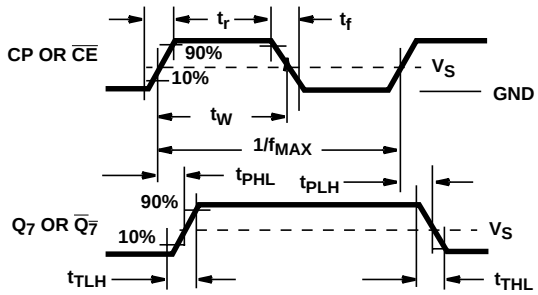


FIGURE 3. SERIAL-SHIFT MODE

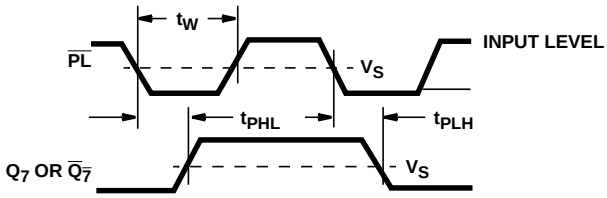


FIGURE 4. PARALLEL-LOAD MODE

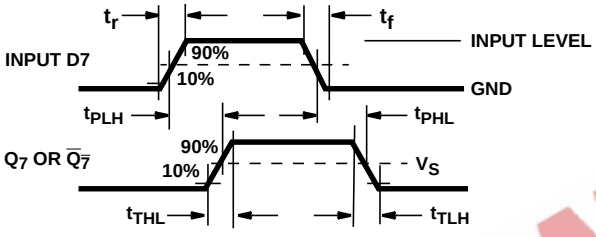


FIGURE 5. PARALLEL-LOAD MODE

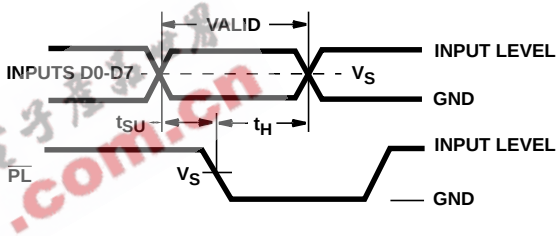


FIGURE 6. PARALLEL-LOAD MODE

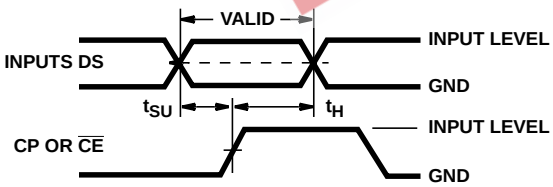


FIGURE 7. SERIAL-SHIFT MODE

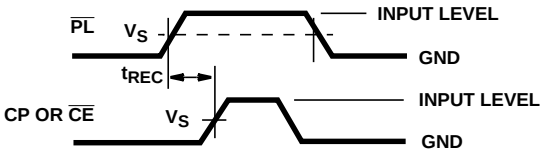


FIGURE 8. SERIAL-SHIFT MODE

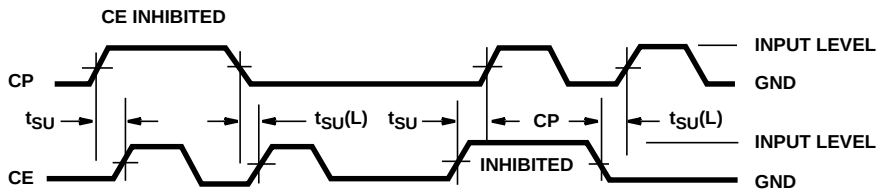


FIGURE 9. SERIAL-SHIFT, CLOCK-INHIBIT MODE

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
5962-8685501EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD54HC165F3A	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD54HCT165F3A	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
CD74HC165E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC165EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC165M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC165M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC165M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC165M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC165ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC165MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC165MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC165MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC165MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT165E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT165EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT165M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT165M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT165M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT165M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT165ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT165MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT165MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT165MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT165MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

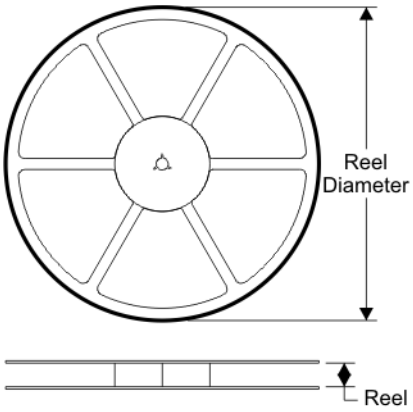
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

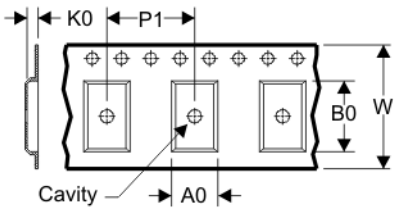
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

TAPE AND REEL BOX INFORMATION

REEL DIMENSIONS

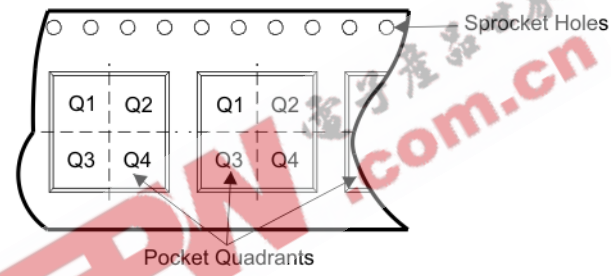


TAPE DIMENSIONS



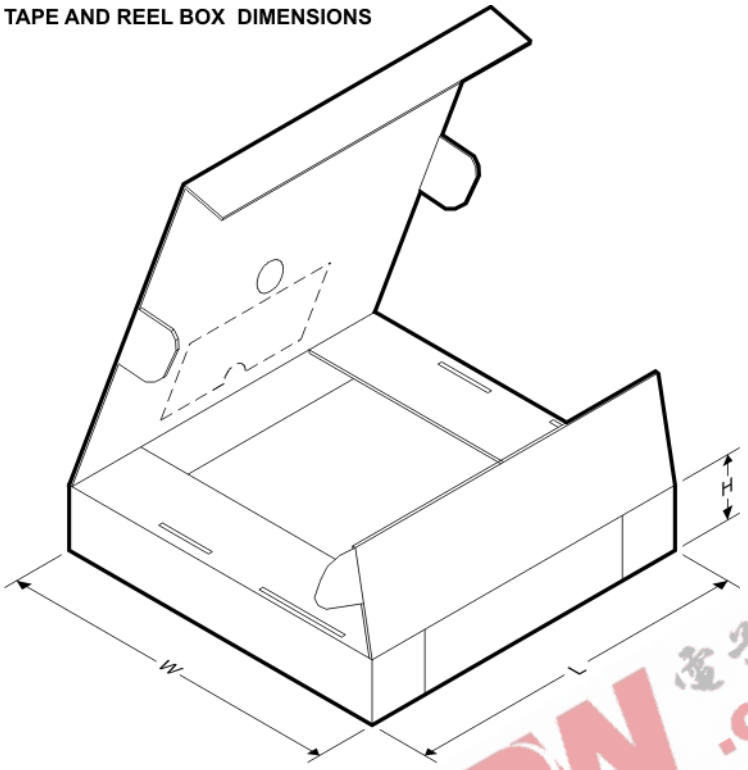
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC165M96	D	16	SITE 27	330	16	6.5	10.3	2.1	8	16	Q1
CD74HC165M96	D	16	SITE 41	330	16	6.5	10.3	2.1	8	16	Q1
CD74HCT165M96	D	16	SITE 27	330	16	6.5	10.3	2.1	8	16	Q1

TAPE AND REEL BOX DIMENSIONS

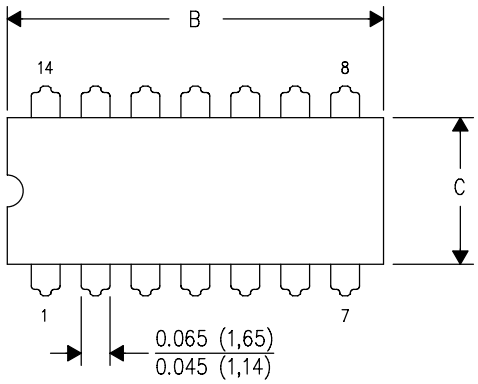


Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
CD74HC165M96	D	16	SITE 27	342.9	336.6	0.0
CD74HC165M96	D	16	SITE 41	346.0	346.0	0.0
CD74HCT165M96	D	16	SITE 27	342.9	336.6	0.0

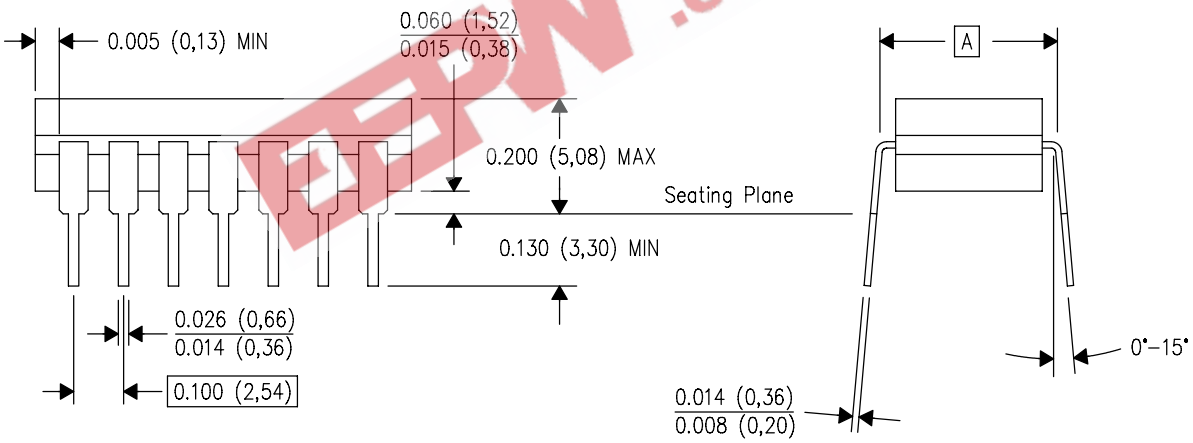
J (R–GDIP–T**)

CERAMIC DUAL IN–LINE PACKAGE

14 LEADS SHOWN



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



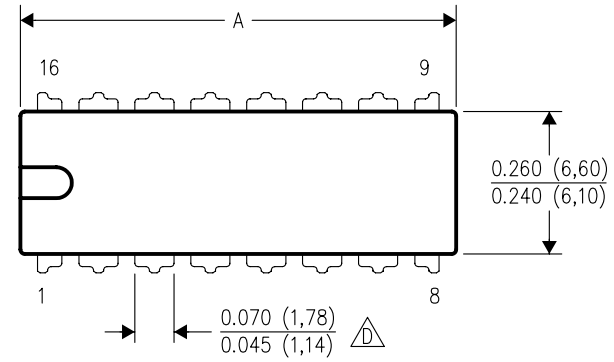
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

N (R–PDIP–T**)

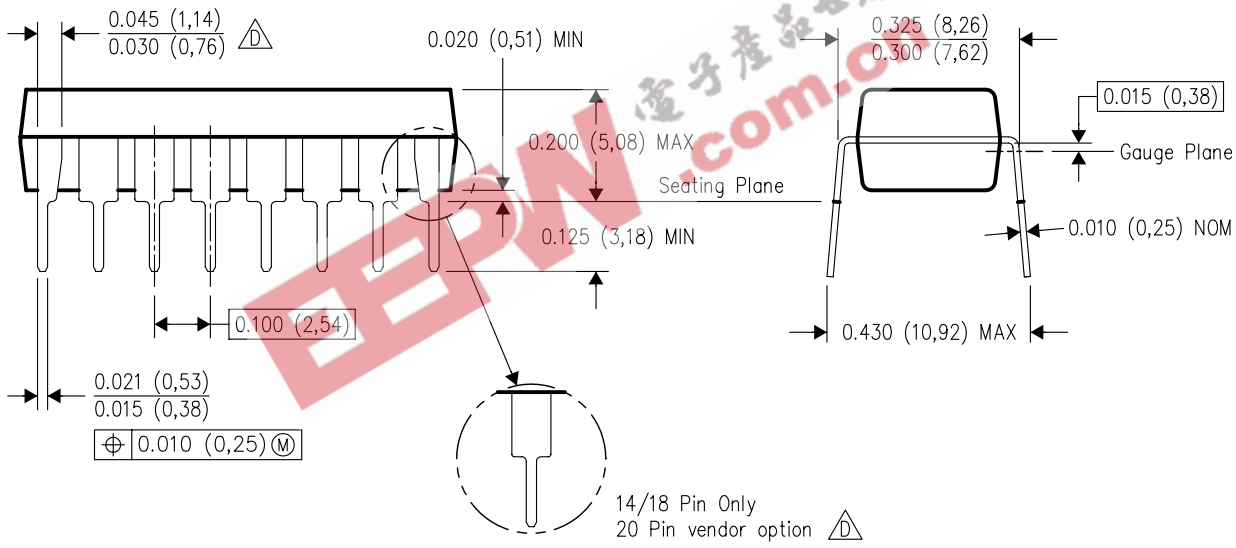
PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION	AA	BB	AC	AD

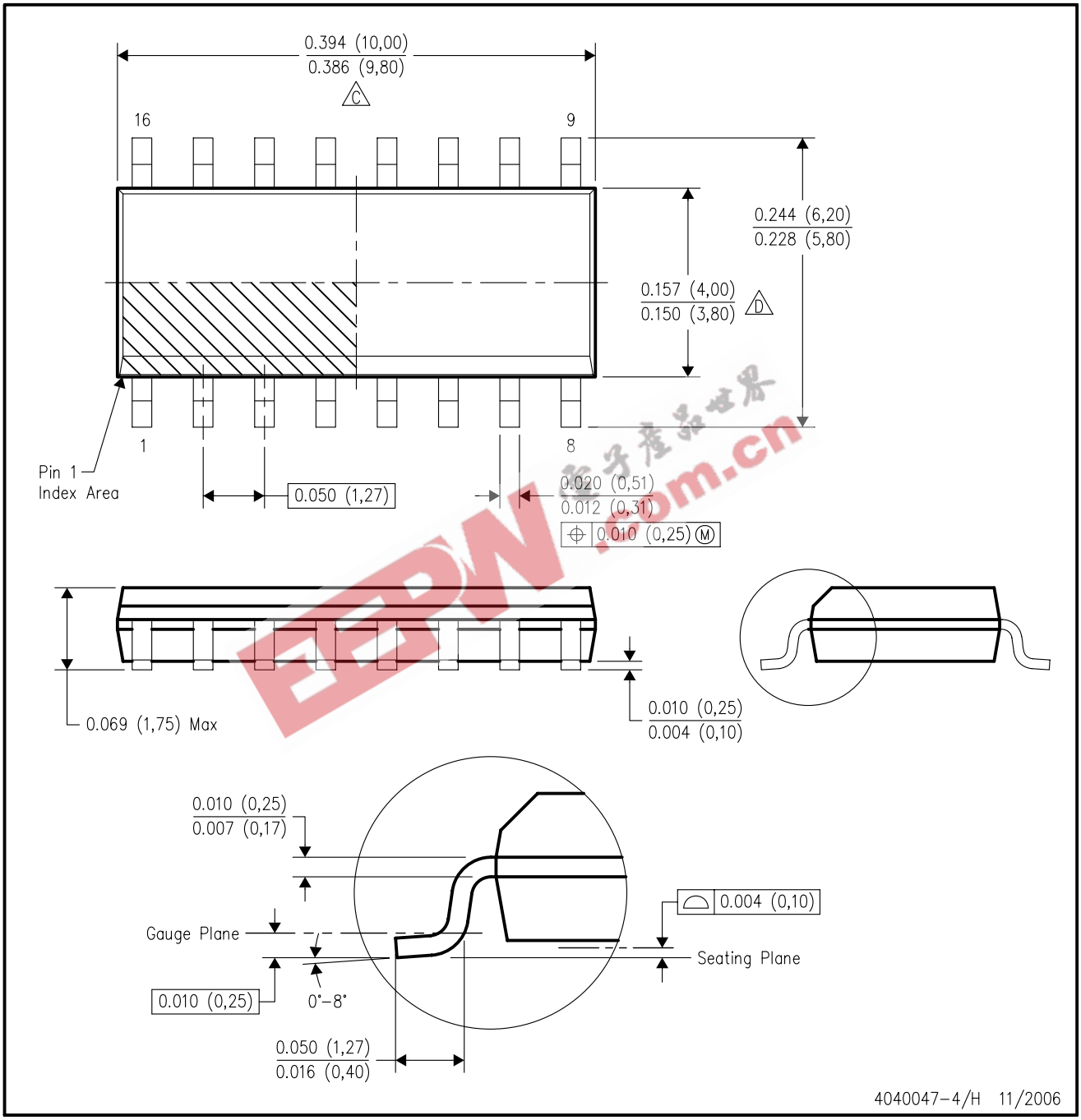
C



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G16) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AC.

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